

Title (en)  
INTEGRATED ELECTRONIC MICROMODULE AND METHOD FOR MAKING SAME

Title (de)  
ELEKTRONISCHER INTEGRIERTER MIKROMODUL UND HERSTELLUNGSVERFAHREN EINES SOLCHEN MIKROMODULS

Title (fr)  
MICROMODULE ELECTRONIQUE INTEGRE ET PROCEDE DE FABRICATION D'UN TEL MICROMODULE

Publication  
**EP 1097479 A1 20010509 (FR)**

Application  
**EP 99925077 A 19990614**

Priority  
• FR 9901405 W 19990614  
• FR 9808426 A 19980629

Abstract (en)  
[origin: FR2780551A1] Electronic micro modules (30) are produced by forming via holes (36-38) in an insulation layer (33, 34) for connecting flat coils (31) to buried chips. Simultaneous production of several electronic micro modules (30), involves: (a) mounting several chips (1) on a wafer (2); (b) depositing a blanket insulation layer (33, 34); (c) forming insulation layer holes (36-38) at the locations of the chip connection pads (4); (d) forming flat coil windings (31) on the support plate; (e) connecting each coil to a corresponding chip; and (f) dicing the plate to individualize the micro modules. Independent claims are also included for the following: (i) an electronic micro module with a chip buried in an insulating layer, on which a coil is provided; and (ii) a hybrid micro module having the above micro module on its back face.

IPC 1-7  
**H01L 23/64**

IPC 8 full level  
**H01L 25/00** (2006.01); **G06K 19/077** (2006.01); **H01L 23/498** (2006.01); **H01L 23/64** (2006.01); **H04B 5/00** (2006.01)

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C-Set (source: EP US)  
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2. **H01L 2224/45144 + H01L 2924/00014**  
3. **H01L 2224/45124 + H01L 2924/00014**  
4. **H01L 2224/45147 + H01L 2924/00**

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